

The NSF Nanoscale Science and Engineering Center
for High-rate Nanomanufacturing
www.nano.neu.edu

Directed Assembly of Nanoelements for the
Nanomanufacturing of Devices



Northeastern
UNIVERSITY



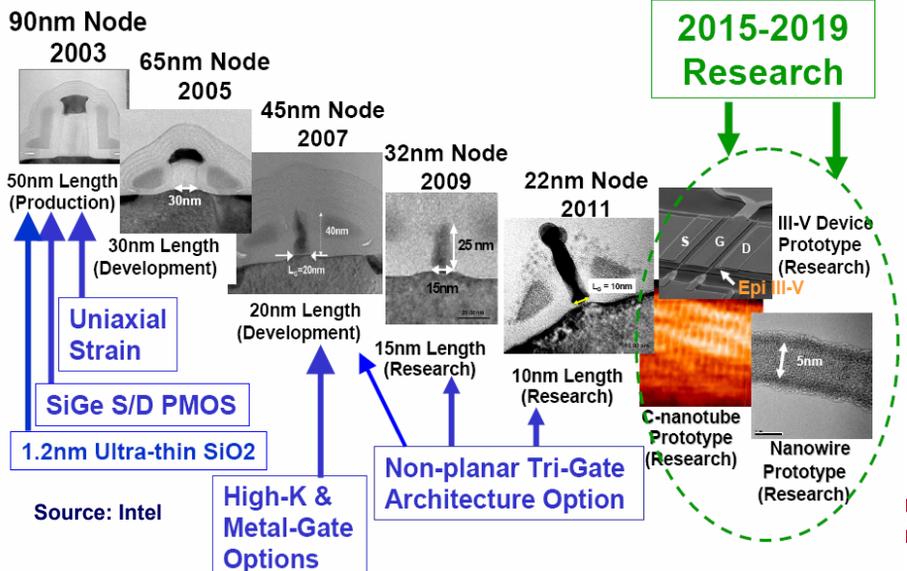
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Outreach Universities: Michigan State University

Collaboration and Outreach: Museum of Science-Boston, City College of New York, Hampton University, Rice University, ETH, Switzerland, Hanyang University and Inje University, Korea The Korean Center for Nanoscale Mechatronics and Manufacturing (CNMM), University of Hyogo, Japan

Beyond the ITRS Roadmap

Transistor Scaling and Research Roadmap



CMOS Scale Limits and Power Considerations

- If the thermal dissipation problem is not solved, we will have to forgo the speed and density that come with nanoelectronics even if we can build very fast and small transistors.
- Even if charge-based devices can be built smaller than CMOS, they can not be operated faster or be cheaper than CMOS.
- Thermal scaling will decide the scaling limit for CMOS. This also means that new (non charge-based) logic devices will be required to go beyond 2020 (beyond CMOS).

What is the solution?

- A new energy efficient, high performance, scalable switch with gain and operational reliability at room temperature that are compatible with CMOS process and architecture.

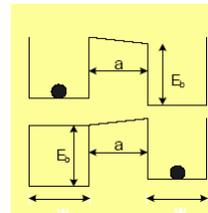


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Nanoelectronics Challenges; Examples of Non-Charge Based Switches

- The room temperature limit is; for 1.5 nm, a switching energy of 0.017 electron volts, and a switching speed of 0.04 pico second.
- The power needed for a 100% duty cycle at the considered limit is a power density of **3.7 million Watts/cm²**.
- If we consider a 1% duty cycle and 1% active transistors, we get a total power density of **370 W/cm²**.

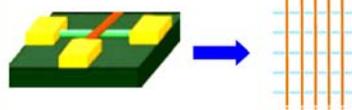
Zhirnov, V., et. al., Proceedings IEEE, Nov. 2003



Many Potential solutions Exist
Alternative state variables

- Spin-electron
- Photon
- Phase
- Quantum state
- Magnetic flux quanta
- Mechanical position
- Dipole orientation
- Molecular state
- Orbital symmetry
- Order/disorder

Extending CMOS Crossed Nanowire Structures:



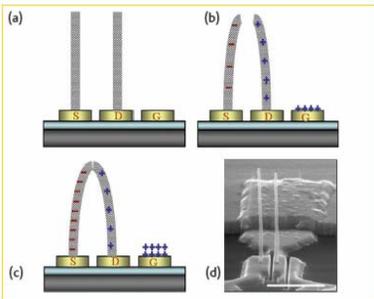
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Nanoelectronics Challenges; Examples of Non-Charge Based Switches

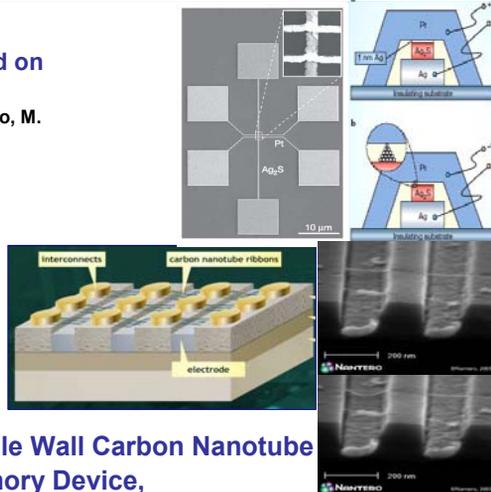
Silver Nanoswitch

Could nanoelectronic devices based on ionic conductors replace silicon?

Terabe, K., Hasegawa, T., Nakayama, T. & Aono, M. *Nature* 433, 47–50 (2005).



(a-c) Schematics showing NEMS switch being biased from 'off' to 'on' states, and (d) scanning electron micrograph showing nanotubes. (© 2005 American Institute of Physics.)



Single Wall Carbon Nanotube Memory Device,

Ward, J.W.; Meinhold, M.; Segal, B.M.; Berg, J.; Sen, R.; Sivarajan, R.; Brock, D.K.; Rueckes, T. *IEEE*, 2004, 34-38.

SWNT Mechanical Switch

Jang et al., *Appl. Phys. Lett.* (2005) 87, 163114.

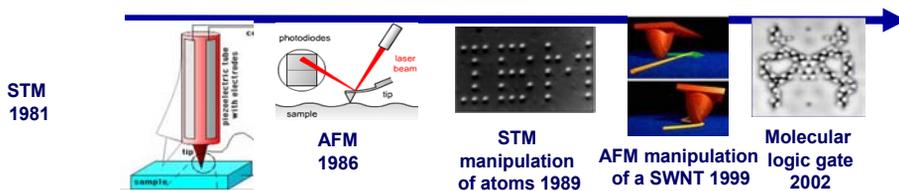


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The Path from Nanoscience to Nanomanufacturing

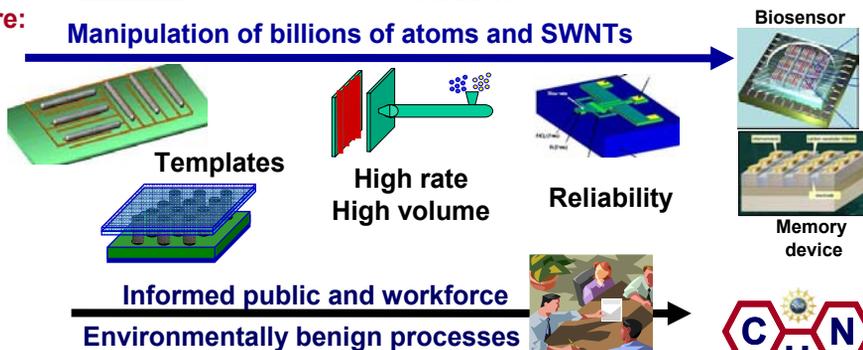
Past and present:

Manipulation of few atoms and SWNTs



Future:

Manipulation of billions of atoms and SWNTs



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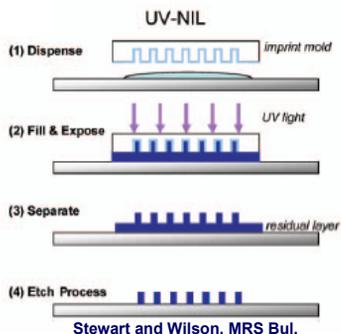
CHN Vision

High-rate Directed Self-Assembly of Nanoelements



State of the Art:

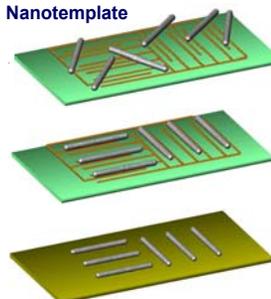
- A pattern is transferred into photoresist. A single mask can be used for thousands of Wafers.



Nanoimprint:

- A pattern is transferred into photoresist using a mold. A mold could also be used for thousands of wafers.

Nanotemplate



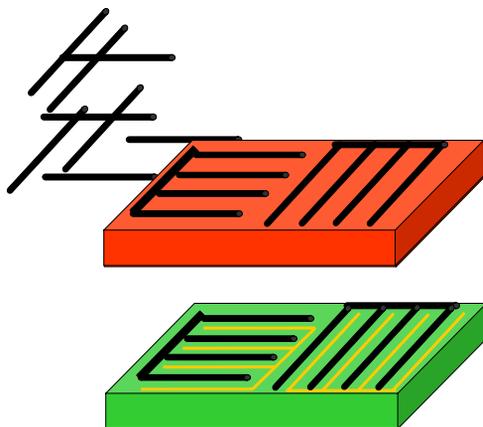
Nanotemplate:

- A layer of assembled nanostructures is transferred to a wafer. A template could also be used for thousands of wafers.



CHN Vision: Guided Self Assembly

High-rate/High-volume Guided Self-Assembly of Nanoelements



➤ State of the Art:

- Pure self-assembly produces regular patterns

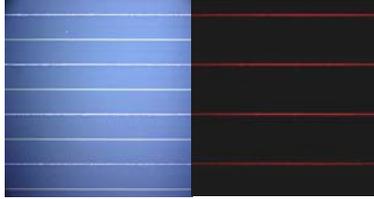
➤ Challenge:

- Nanotemplates enable guided self assembly



Electrostatic Assembly of Nanoparticles

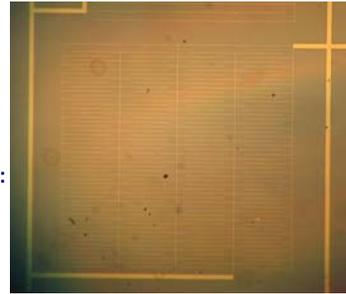
Assembly of 300 nm PSL particles (negatively charged) on positively-charged Au microwires



bright field

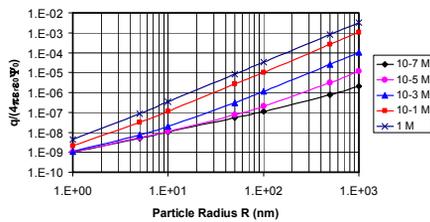
dark field

Current
Template size is:
2.25 - 4.00 cm²

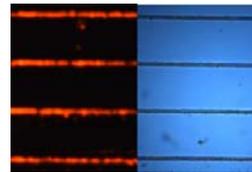


Microfingers on the template.

Computational fluid dynamic (CFD) model to aid in preparing templates with uniform deposition



The dependence of surface charge on particle size and mol concentration of liquid



dark field

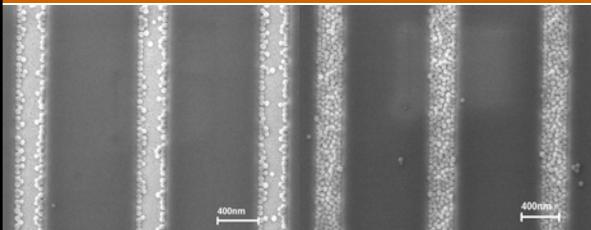
bright field

PSL Fluorescent Particles

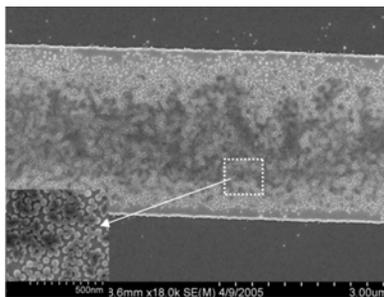


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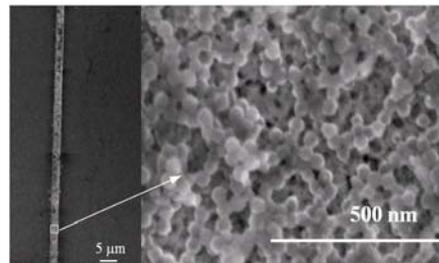
Electrostatic Assembly of Nanoparticles



50 nm PSL particles assembled in trenches. (left) partial coverage in 260 nm wide trenches at 2 V for 30 seconds; (right) full coverage in 260 nm wide trenches at 3 V DC for 90 seconds.



50 nm particle assembly in a monolayer

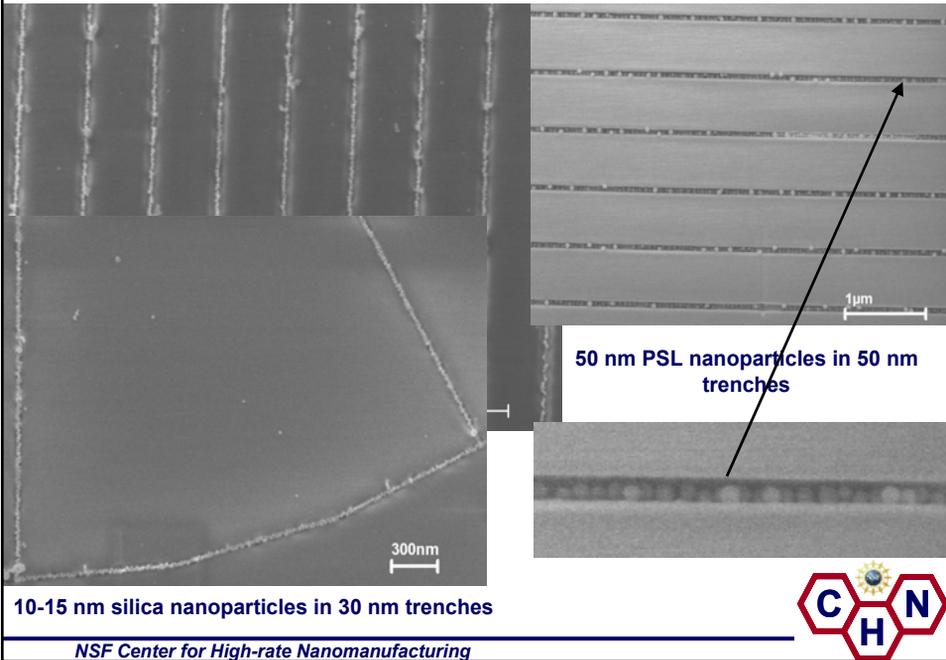


50 nm PSL nanoparticles assembly in multi-layers

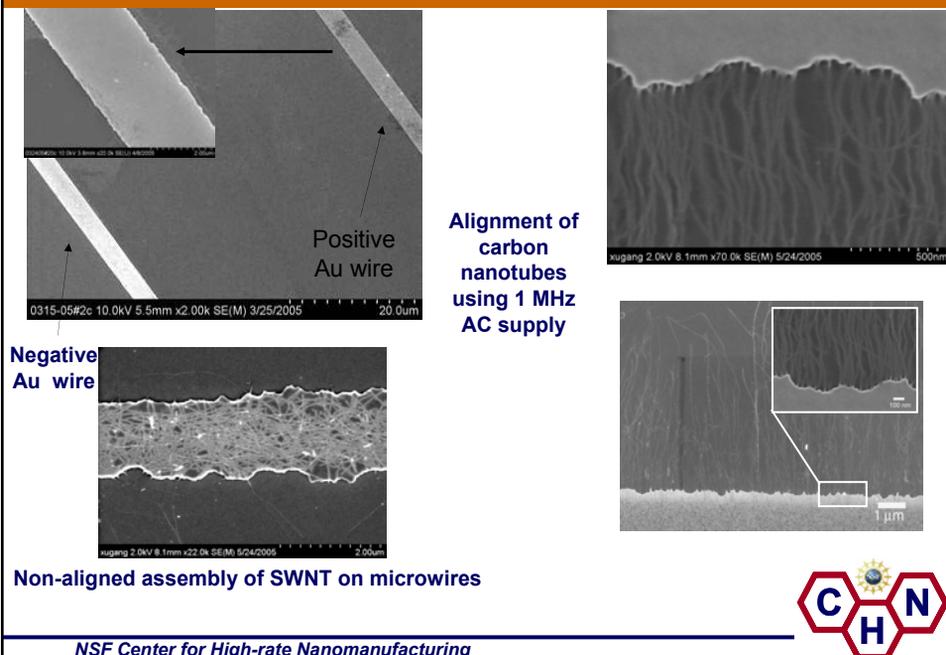


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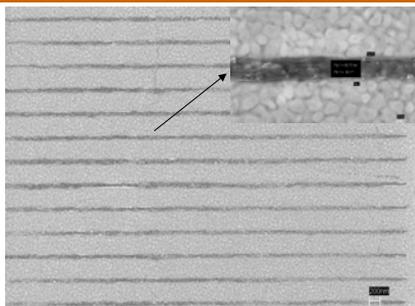
Electrostatic Assembly of Nanoparticles



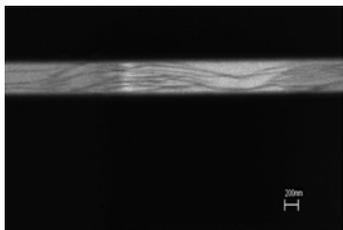
Electrostatic Assembly of SWNT



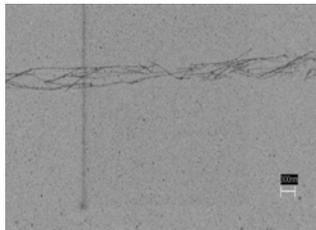
Electrostatic Assembly of SWNT in Trenches



Assembly into sub 100 nm trenches with 5 V for 1 minute



SWNTs Assembled within polymer trenches



SWNT on gold after dissolving polymer

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Highlights of Guided Self-Assembly of Polymer Melts at High Rates

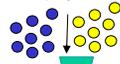
Use nanotemplates in high rate environment

Nanotemplates used as tooling surface in high rate process

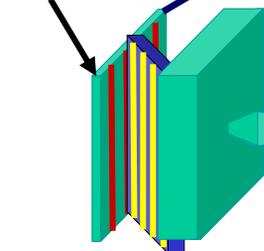


microinjection molding machine

Polymer A + B
Blends/block copolymers



Injection Molder



Complex shapes can be manufactured

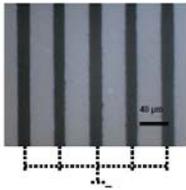


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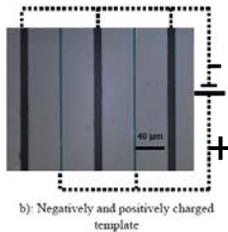


Assembly of Polymer Using Electrostatically Addressable Templates

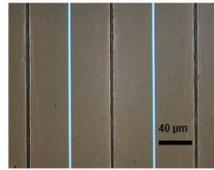
Conducting Polymer – Polyaniline (PANI)



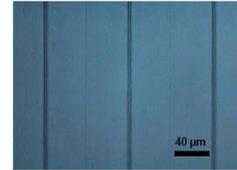
a) Negatively charged Template



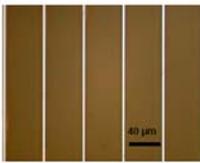
b) Negatively and positively charged template



a) PANI-assembled template

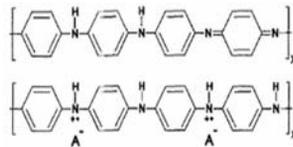


b) PU film with patterned PANI



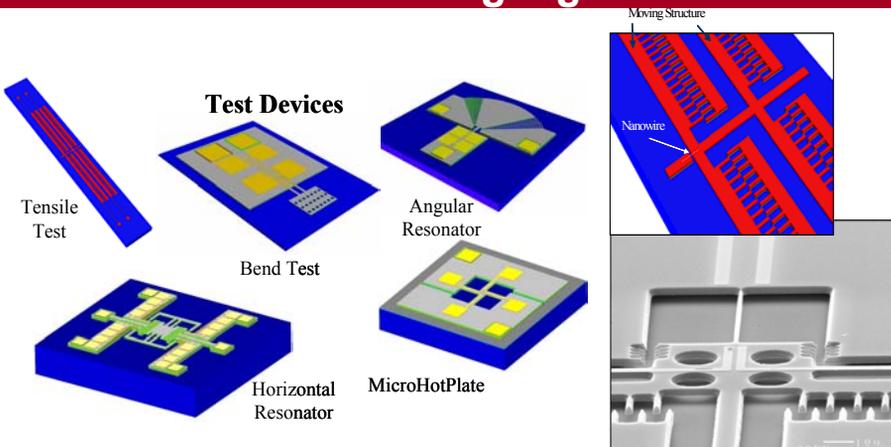
c) Template w/o charge

Transfer of assembled PANI nanowires to PS and PU polymer substrates



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Nanoscale Characterization and Reliability Testbed Highlights



Innovative MEMS devices characterize nanowires (also nanotubes, nanorods and nanofibers) and conduct accelerated lifetime testing allowing rapid mechanical, electrical, and thermal cycling during UHV SPM observation



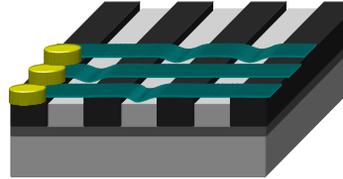
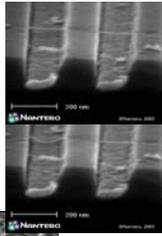
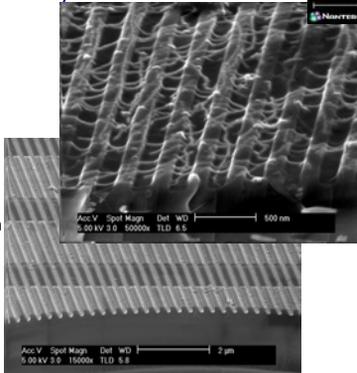
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High Density Memory Chip

Current process

- Uses conventional optical lithography to pattern carbon nanotube films
- Switches are made from belts (ribbons) of nanotubes

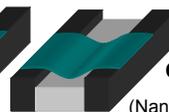
Electrodes
(~100nm
with 300 nm
period)



OFF state



ON state



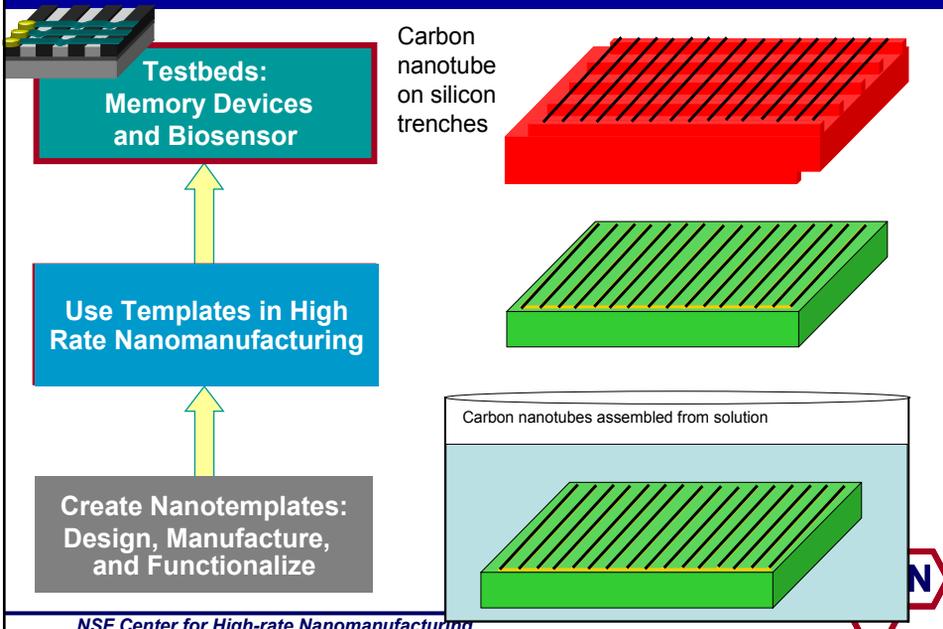
(Nantero, 2004)

Nanotemplate will enable single CNT
electromechanical switch



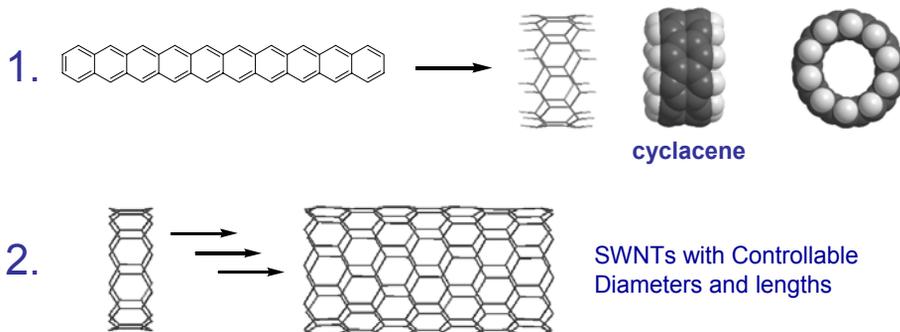
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Q1b. How does concept design translate into high-rate manufacturing and how is it validated through the testbeds?



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High Volume Wet Chemical Synthesis of SWNTs with Uniform, Tunable Properties

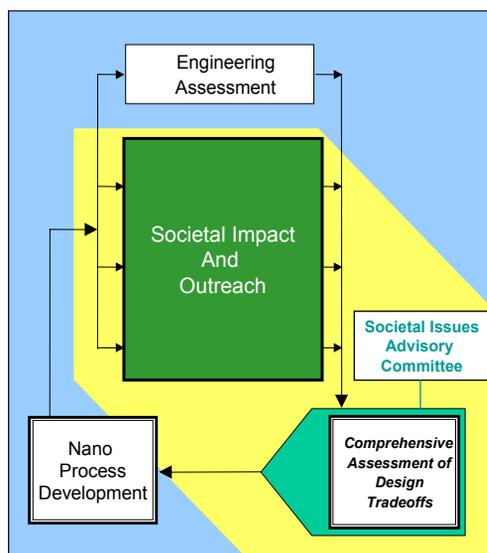


Cyclacene precursors, both acenes and fullerene-acene adducts, have been synthesized.



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Concurrent Assessment Processes



- Full systems analysis to assess technology development of nanotemplating
- Create environmentally benign processes and products
- Identify significant cost barriers
- Inform policymakers and generate public discourse during process development
- Establish comprehensive assessment practices for success of technology



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Partnerships

Industry



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Team Strength and Synergy

NEU

- MEMS, fabrication, nanoscale contamination control



Semiconductor & MEMs fab

- 10,000 ft² class 10 and 100 cleanroom
- 6 inch completer Wafer fab, nanolithography capabilities

UML

- High volume polymer processing



Plastics processing labs

- 40,000 ft² +
- Compounding, and forming equipment



A unique partnership

UNH

- Synthesis, self-assembly



Fully-equipped synthetic labs

- 10,000 ft² +

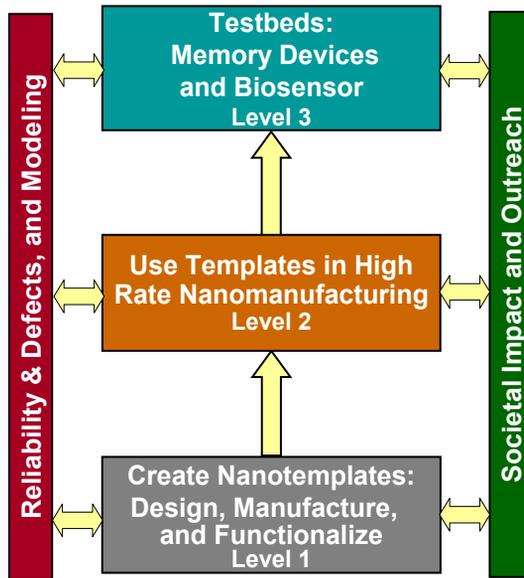
Characterization labs at NEU, UNH and UML:

- material characterization and analysis including STM/AFM, NSOM, SIMS, SEM, TEM, XRD, AEM, XPS,



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CHN's Path to Nanomanufacturing



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